

[ABSTRACT]

~~In order to improve step coverage of a film formed in a formation pattern on a substrate, the present invention is configured so as to perform:~~ According to one aspect of the technique of the present disclosure, there is provided a substrate processing method including: a step for accommodating a substrate retainer, in a processing chamber, including: a substrate holding tool having a substrate support; ~~tool that supports a substrate,~~ and a partition plate support capable of supporting ~~tool that supports an upper partition plate positioned provided above a substrate on the upper part of the substrate that is supported by~~ the substrate support ~~tool;~~ setting a distance between the substrate and the upper partition plate to a first gap; supplying a first gas ~~supply step in which~~ to the substrate through a gas supply port in a state where the distance between the substrate and the upper partition plate is set to a first distance maintained at the first gap, and a first gas is supplied to the substrate ~~through a gas supply opening;~~ and a second gas supply step in which setting the distance between the substrate and the upper partition plate is set to a second distance gap; and supplying a second gas is supplied to the substrate through the gas supply port in a state where the distance between the substrate and the upper partition plate is maintained at the second gap opening.